



## Description

The HXY80N03D uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

## General Features

$V_{DS} = 30V$   $I_D = 80A$

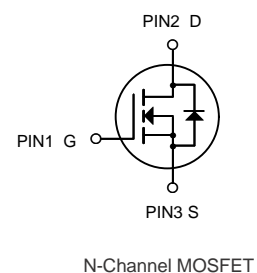
$R_{DS(ON)} < 6.8m\Omega @ V_{GS}=10V$

## Application

Battery protection

Load switch

Uninterruptible power supply



## Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
HXY80N03D	TO252-2L	80N03D XXX YYYY	2500

## Absolute Maximum Ratings ( $T_C=25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	30	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Drain Current – Continuous ( $T_C=25^{\circ}C$ )	80	A
	Drain Current – Continuous ( $T_C=100^{\circ}C$ )	51	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	320	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	88	mJ
IAS	Single Pulse Avalanche Current <sup>2</sup>	42	A
$P_D$	Power Dissipation ( $T_C=25^{\circ}C$ )	54	W
	Power Dissipation – Derate above $25^{\circ}C$	0.43	W/ $^{\circ}C$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^{\circ}C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^{\circ}C$
$R_{\theta JA}$	Thermal Resistance Junction to ambient	62	$^{\circ}C/W$
$R_{\theta JC}$	Thermal Resistance Junction to Case	2.3	$^{\circ}C/W$



Electrical Characteristics ( $T_J=25^{\circ}\text{C}$ , unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	$V_{GS}=0V$ , $I_D=250\mu A$	30	---	---	V
$\Delta BVDSS/\Delta T_J$	$BV_{DSS}$ Temperature Coefficient	Reference to $25^{\circ}\text{C}$ , $I_D=1mA$	---	0.04	---	$V/^{\circ}\text{C}$
IDSS	Drain-Source Leakage Current	$V_{DS}=30V$ , $V_{GS}=0V$ , $T_J=25^{\circ}\text{C}$	---	---	1	$\mu A$
		$V_{DS}=24V$ , $V_{GS}=0V$ , $T_J=125^{\circ}\text{C}$	---	---	10	$\mu A$
IGSS	Gate-Source Leakage Current	$V_{GS}=\pm 20V$ , $V_{DS}=0V$	---	---	$\pm 100$	nA
RDS(ON)	Static Drain-Source On-Resistance <sup>3</sup>	$V_{GS}=10V$ , $I_D=20A$	---	5	6.8	$m\Omega$
		$V_{GS}=4.5V$ , $I_D=10A$	---	6.5	9	$m\Omega$
VGS(th)	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=250\mu A$	1	1.6	2.5	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	-4	---	$mV/^{\circ}\text{C}$
gfs	Forward Transconductance	$V_{DS}=10V$ , $I_D=10A$	---	18	---	S
$Q_g$	Total Gate Charge <sup>3, 4</sup>	$V_{DS}=15V$ , $V_{GS}=4.5V$ , $I_D=20A$	---	11.1	---	nC
$Q_{gs}$	Gate-Source Charge <sup>3, 4</sup>		---	1.85	---	
$Q_{gd}$	Gate-Drain Charge <sup>3, 4</sup>		---	6.8	---	
$T_{d(on)}$	Turn-On Delay Time <sup>3, 4</sup>	$V_{DD}=15V$ , $V_{GS}=10V$ , $R_G=3.3\Omega$ $I_D=15A$	---	7.5	---	ns
$T_r$	Rise Time <sup>3, 4</sup>		---	14.5	---	
$T_{d(off)}$	Turn-Off Delay Time <sup>3, 4</sup>		---	35.2	---	
$T_f$	Fall Time <sup>3, 4</sup>		---	9.6	---	
Ciss	Input Capacitance	$V_{DS}=25V$ , $V_{GS}=0V$ , $F=1MHz$	---	1160	---	pF
Coss	Output Capacitance	$V_{GS}=0V$ , $V_{DS}=0V$ , $F=1MHz$	---	200	---	$\Omega$
Crss	Reverse Transfer Capacitance		---	180	---	
$R_g$	Gate resistance		---	2.5	---	
EAS	Single Pulse Avalanche Energy	$V_{DD}=25V$ , $L=0.1mH$ , $I_{AS}=20A$	20	---	---	mJ
IS	Continuous Source Current	$V_G=V_D=0V$ , Force Current	---	---	80	A
ISM	Pulsed Source Current <sup>3</sup>		---	---	320	A
VSD	Diode Forward Voltage <sup>3</sup>	$V_{GS}=0V$ , $I_S=1A$ , $T_J=25^{\circ}\text{C}$	---	---	1	V
trr	Reverse Recovery Time	$V_{GS}=0V, I_S=1A$ , $di/dt=100A/\mu s$ $T_J=25^{\circ}\text{C}$	---	---	---	ns
$Q_{rr}$	Reverse Recovery Charge		---	---	---	nC

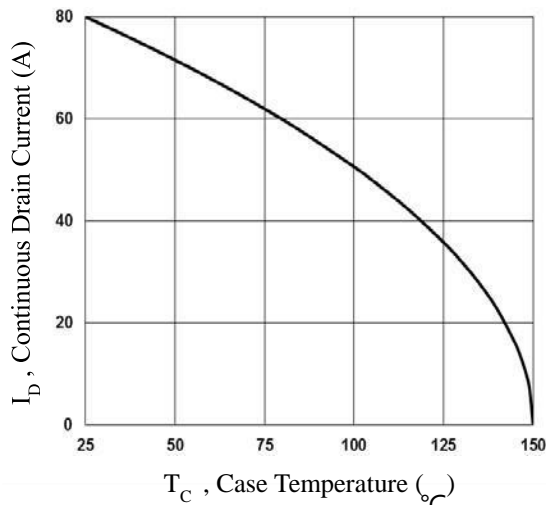


Fig.1 Continuous Drain Current vs. Tc

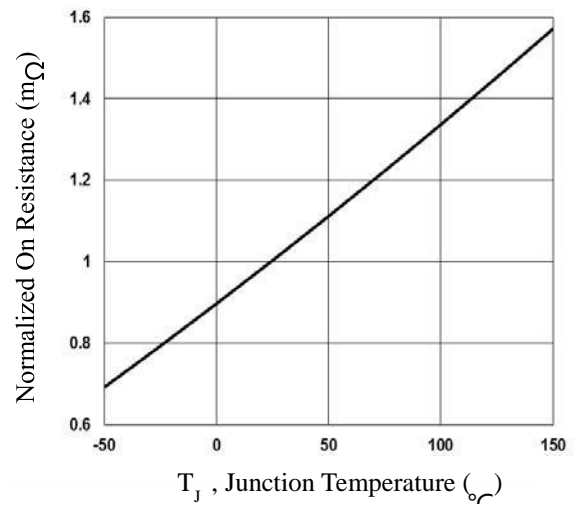


Fig.2 Normalized RDSON vs. Tj

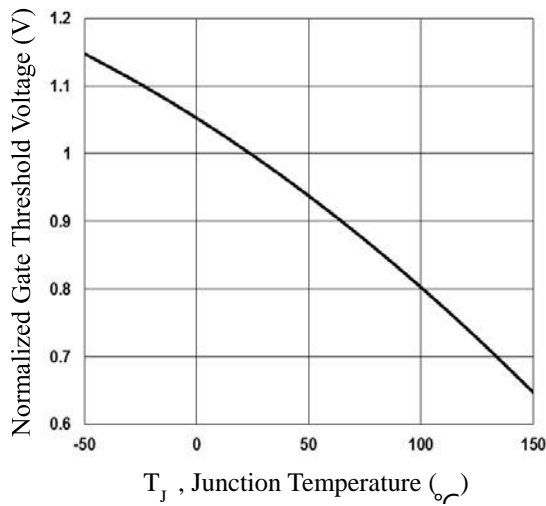


Fig.3 Normalized Vth vs. Tj

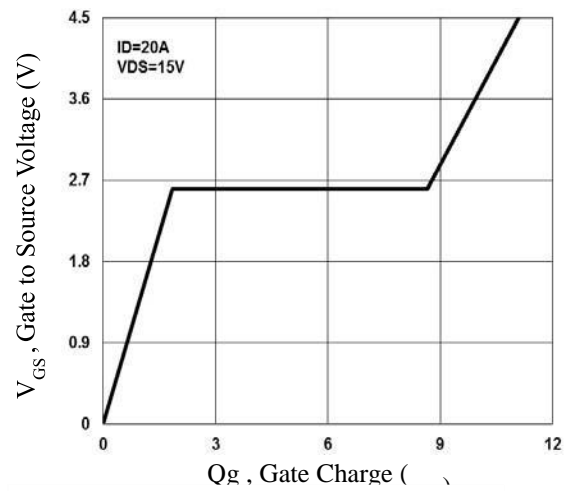


Fig.4 Gate Charge Waveform

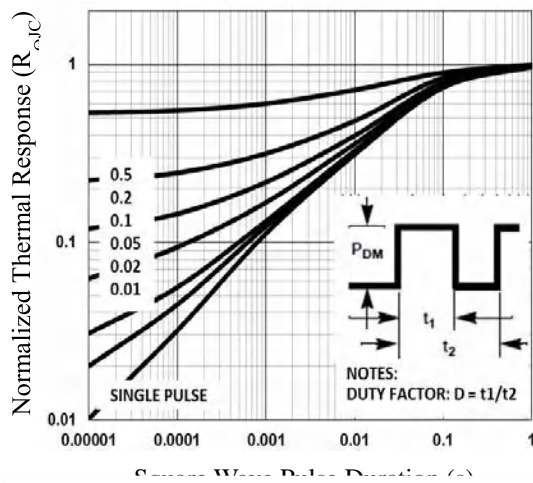


Fig.5 Normalized Transient Impedance

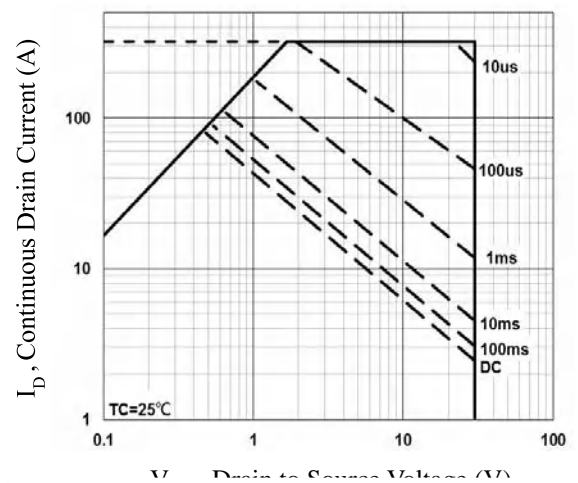


Fig.6 Maximum Safe Operation Area

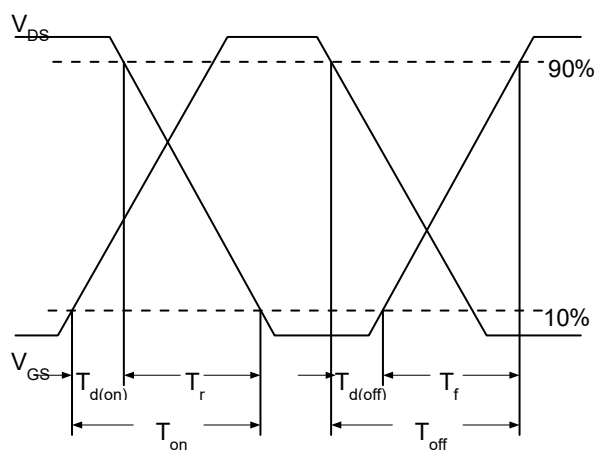


Fig.7 Switching Time Waveform

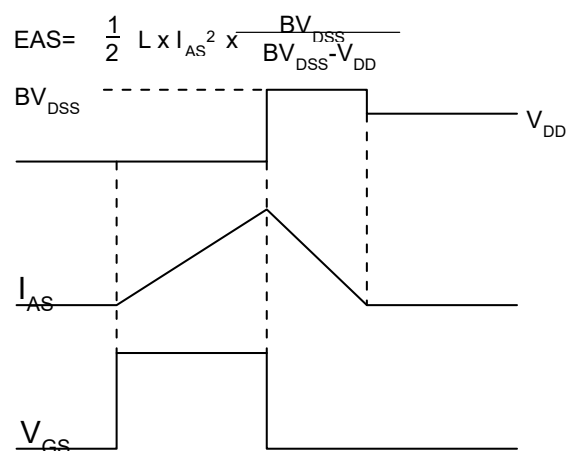
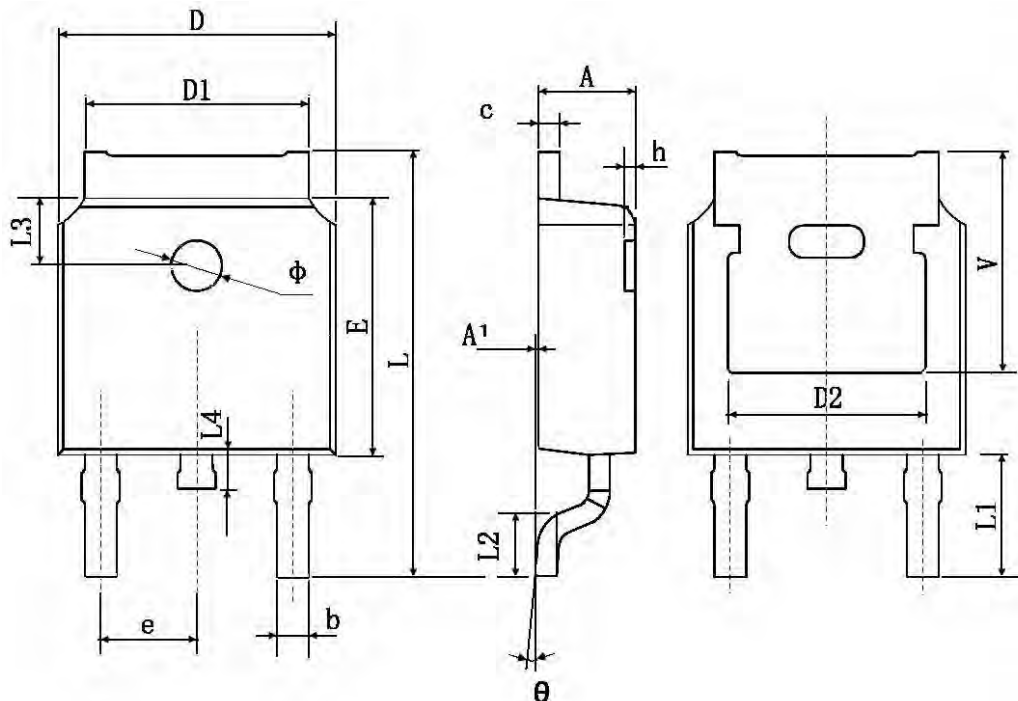


Fig.8 EAS Waveform



## N-Channel Enhancement Mode MOSFET



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	0.483 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	



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